



Space Passive Component Days – Preliminary Programme Tuesday 11th October 2022

Start Time	End Time	Title
08:30	09:30	Registration Desk Opening
09:30	12:00	ESCC training course - Part I
12:00	13:00	Lunch
13:00	16:00	EEE Passives Seminar
		ESCC training course - Part II
16:00	18:00	ESA Site Tour & Space Expo Museum <i>Only available to pre-registered participants</i>

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Wednesday 12th October 2022

Start Time	End Time	Topic	Title	Company
08:30	09:30		Registration Desk Opening	
09:30	09:50		Welcome Speech	
09:50	10:10		Introduction & Instructions Speech	
10:10	10:40	Technology Roadmaps	Space Passive Components : Activities, News and Trends	ESA/ESTEC Netherlands
10:40	11:00	Commercial Off-The-Shelf (COTS)	Assessment of ECSS-Q-ST-60-13 for COTS Passive Components	Alter Technology Spain
11:00	11:30		Networking Break	
11:30	11:50	Application, Trends & Needs	Supercapacitors for space applications: trends and opportunity	ESA ESTEC, Netherlands
11:50	12:10		Improving RF connectivity for space application in Telecom satellites in production environment	Airbus DS UK
12:10	12:30		Resistive and Wilkinson power splitters at frequencies of millimeter waves for space applications	Smiths Interconnect, USA
12:30	13:00	Technical Introduction of Components (TICs) <i>7min per TIC</i>	New Micro-D Connector Series	C&K Components France
			24-fibers interconnect solutions for payload data processing	Radiall France
			Real breakthroughs in Ta caps technology critical for space applications	Kemet Yageo USA
			RADATOX™ - New Space ATOX resistant wires and cables	Axon Cable France
13:00	14:30	Lunch		
14:00	14:30	Manufacturers' Private Roadmap Parallel Sessions <i>Rooms n° Aj 019/ Aj 020</i>	AXTAL GmbH & Co. KG Private Roadmap Session	SOURIAU SAS Private Roadmap Session
14:30	15:30	Dedicated Poster Session		
15:30	16:00	Technical Introduction of Components (TICs) <i>7min per TIC</i>	Smiths Interconnect Filters Planar X series for Space Applications	Smiths Interconnect France
			JAXA qualified MDM Connector introduction	ITT Cannon Japan
			Fuel Pipes Heating system, On Exomars Landers	THERMOCOAX France
16:00	16:20	New Developments	Novel Graphene Material for High Energy Storage Supercapacitors	EPCI Czech Republic
16:20	16:40		Miniaturization of high voltage MLCC for space applications	Exxelia France
16:40	17:00		High Energy Density Solid State Polymer Capacitors for Space Applications	PolyCharge America USA
17:00	17:20		Low profile and solderless solutions for flat space interconnect	Axon' Cable Ltd, Great Britain
17:20	17:40		AFSIW Y-junction Circulator for High-power Handling New Space Applications	Cobham France
17:40	18:00	Lessons Learned or In-flight Experiences	Passive EEE parts in the Biomass Payload: challenges and lessons learned	ESA/ESTEC Netherlands
18:00	20:00	Welcome Drink		

Space Passive Component Days – Preliminary Programme

Thursday 13th October 2022

Start Time	End Time	Topic	Title	Company
08:30	09:00	Session Chair & Introduction		
09:00	09:20	Technology Roadmaps	TAS Road Map	THALES ALENIA SPACE, France
09:20	09:40	Test, Reliability & Evaluation for space	Feedback from 10 years of Failure Analysis on connectors – all electronic sectors	Serma Technologie France
09:40	10:00	New Developments	Exxelia new MML technology for film capacitors miniaturization	EXXELIA France
10:00	10:20		Miniature RF switch for compact redundancy ring	RADIALL SA France
10:20	10:40	Evaluation & Qualification	Power surge testing for polymer tantalum capacitors	Jacobs Technology Inc., USA
10:40	11:00	Normative System & Standards	Harness sizing approach for bundles equipped with shields	Airbus Defence and Space, France
11:00	11:30	Networking Break		
11:30	11:50	Application, Trends & Needs	Supercapacitor for launcher applications	ALMATECH SA Switzerland
11:50	12:10	Commercial Off-The-Shelf (COTS)	The latest activities related to the passive components in JAXA	JAXA Japan
12:10	12:30		Proba 3 Mission: ISL Architecture and procurement approach for Passives COTS	ESA/ESTEC Netherlands
12:30	13:00	Technical Introduction of Components (TICs) <i>7min per TIC</i>	European Passive Components Institute Introduction and PCNS invitation	EPCI Czech Republic
			KVPX - High Speed Backplane Press-Fit Connector	Smiths Interconnect France
			Kyocera AVX High Reliability Components	Kyocera-AVX Ltd Great Britain
			Miniaturized integrated TX/RX feed chain at Ku band	MinWave Switzerland
13:00	14:30	Lunch		
14:30	15:00	Technical Introduction of Components (TICs) <i>7min per TIC</i>	ESCC qualified platinum thin film temperature sensors with cable extension	IST AG Switzerland
			New micro-miniature connector solutions	Axon' Cable Ltd Great Britain
			High power S-band coaxial isolator development at TKI-Ferrit Ltd	TKI-Ferrit Ltd Hungary
			Miniature Temperature Compensated Crystal Oscillators in COTS Technology	AXTAL GmbH & Co. KG - Germany
15:00	15:20	New Developments	HYPERBITS Connector Design and Qualification for High Reliability CPCI SERIAL SPACE Applications	MINDREACH i2i SL Andorra
15:20	15:40	Test, Reliability & Evaluation for space	Why qualify Press-Fit Contacts for Spaceflight Applications	AMPHENOL Positronic France
15:40	16:00	Materials and Processes	New Space ESD-Resistant smart-antistatic wires and cables insulations	Axon Cable France
16:00	16:20		Ka-band compact multi-materials rectangular waveguide loads	Lab-STICC / UBO France
16:20	16:40	New Developments	A new modular micro-D connector for high speed data and RF	Glenair UK LTD UK
16:40	17:00	Networking Break		
17:00	18:00	Interactive Panel Discussion	"Long Lead Items: shortage, challenges and potential improvements"	
19:30	01:00	Gala Dinner @ Beach Pavilion "De Zeemeeuw", Noordwijk		

Space Passive Component Days – Preliminary Programme

Friday 14th October 2022

Start Time	End Time	Topic	Title	Company
08:30	09:00	Session Chair & Introduction		
09:00	09:20	Technology Roadmaps	Airbus DS Road-map	Airbus Defence and Space, France
09:20	09:40	New Developments	Thin film diamond thermistors for space environment applications	University of Aveiro Portugal
09:40	10:00		New generation of wafer-scale, hermetically sealed chip fuses for space	SCHURTER AG Switzerland
10:00	10:20		CCM, a family of magnetic components dedicated to space applications and optimized for multi-output flyback converters	Exxelia France
10:20	10:40		Advances in Hermetic Space Grade Tantalum Polymer Capacitors	Kyocera AVX components Czech Republic
10:40	11:10	Networking Break		
11:10	11:30	New Developments	Novel Single-piece miniature coax for transmission of signals to 67 GHz	Smiths Interconnect USA
11:30	11:50	Lessons Learned or In-flight Experiences	Details are important. How can the designer help to make cleaning assemblies easy?	PBT Works s.r.o Czech Republic
11:50	12:10		Platinum sensors embedded in ESCC-4006/014 modified construction: a turbulent tale about the coexistence of dissimilar materials	OHB System AG Germany
12:10	12:30	New Developments	ESA recent activities on thermal parts: development and inspection techniques	ESA/ESTEC Netherlands
12:30	12:50		Lightest and Smallest Low Earth Orbit Wires and Cables Type LEW according to ESCC 3901/026	W. L. Gore & Associates GmbH Germany
12:50	13:10	Closing Session & Award Ceremony		
13:10	14:30	Lunch		



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Poster Session

Wednesday 12th October 2022 @14h30

Title	Company
Space Rated Optical Cables - Rugged solutions to meet the future of space exploration	AirBorn Great Britain
Results on Radiation Testing of Space-COTS TCXOs and OCXOs	AXTAL GmbH & Co. KG Germany
Qualification of Multi-Fiber Interconnect Solutions for payload data processing	Radiall France
Pb-free Ceramic Capacitors for RoHS Reflow	Exxelia France
LOW Phase Noise VHF Oscillator (LNMO-VHF)	OROLIA Switzerland SA Switzerland
Low ESR Polymer Tantalum Capacitors for Space Applications	Kyocera-AVX Czech Republic
FALCOS - SMA Compatible Fast Locking Connector	Progetti Speciali Italiani Italy
EVALUATION OF KA BAND SMD ISOLATOR FOR SPACE APPLICATIONS	Cobham France
Design and manufacturing of the cryogenic detector package for the LAPD detector	ESA/ESTEC Netherlands
Cryogenic characterization of COTS silicon capacitors	ESA/ESTEC Netherlands